



<b>Session Title:</b>	<b>[WeA3] Advanced Cleaning Technology</b>
<b>Session Date:</b>	<b>November 13 (Wed.), 2024</b>
<b>Session Time:</b>	<b>16:05-18:00</b>
<b>Session Room:</b>	<b>Room A (Capri Room, 2F, Paradise Hotel Busan)</b>
<b>Session Chair:</b>	<b>Prof. Jea-Gun Park (Hanyang Univ., Korea)</b>

**[WeA3-1] [Plenary]** **16:05-16:50**

**Recent Advancements In Cleans Technology to Reduce Particle Defectivity and Corrosion**

Paul Bernatis (Hayward, USA), Ping Hsu, Peter Sun, and Jacky Cheng (Hsinchu, Taiwan)

**[WeA3-2] [Invited]** **16:50-17:20**

**Paradigm Changes in Semiconductor Cleaning**

Kuntack Lee, SungHwan Chung, JiHoon Cha, Hayoung Jeon, Seok Heo, SangMin Lee, KiHyung Ko, KeeSang Kwon, JaeJik Baek, ByungKwon Cho, WooRim Lee, SunJung Kim, and JongMyeong Lee (Samsung Electronics Co., Ltd., Korea)

**[WeA3-3]** **17:20-17:40**

**Post CMP Cleaning Solution for Removal of Ceria Nanoparticles**

Chanmi Kim, Saem Hwang, and Jaesung Lee (Soulbrain Co., Ltd., Korea)

**[WeA3-4]** **17:40-18:00**

**Investigating the Role of Benzotriazole on Silica and Copper Ions Loading to Polyvinyl Acetal (PVA) Brush during Copper Post-CMP Cleaning**

Sanjay Bisht, Maheepal Yadav, Se-Hoon Park, Tae-Gon Kim, and Jin-Goo Park (Hanyang Univ., Korea)